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**Preskusne metode za električne materiale, tiskana vezja in druge povezovalne strukture in sestave - 2-807. del: Preskusne metode za materiale, namenjene uporabi v povezovalnih strukturah - Temperatura razgradnje s termogravimetrično analizo**

Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 2-807: Test methods for materials for interconnection structures - Decomposition Temperature (Td) using TGA

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**Ta slovenski standard je istoveten z: EN IEC 61189-2-807:2021**

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**ICS:**

31.180	Tiskana vezja (TIV) in tiskane plošče	Printed circuits and boards
31.190	Sestavljeni elektronski elementi	Electronic component assemblies

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EUROPEAN STANDARD

EN IEC 61189-2-807

NORME EUROPÉENNE

EUROPÄISCHE NORM

October 2021

ICS 31.180

English Version

Test methods for electrical materials, printed boards and other  
interconnection structures and assemblies - Part 2-807: Test  
methods for materials for interconnection structures -  
Decomposition temperature ( $T_d$ ) using TGA  
(IEC 61189-2-807:2021)

Méthodes d'essai pour les matériaux électriques, les cartes  
imprimées et autres structures d'interconnexion et  
ensembles - Partie 2-807: Méthodes d'essai des matériaux  
pour structures d'interconnexion - Température de  
décomposition ( $T_d$ ) par analyse thermogravimétrique  
(IEC 61189-2-807:2021)

Prüfverfahren für Elektromaterialien, Leiterplatten und  
andere Verbindungsstrukturen und Baugruppen - Teil 2-  
807: Prüfverfahren für Materialien für  
Verbindungsstrukturen - Zersetzungstemperatur ( $T_d$ ) unter  
der Nutzung von TGA  
(IEC 61189-2-807:2021)

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European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

**EN IEC 61189-2-807:2021 (E)****European foreword**

The text of document 91/1697/CDV, future edition 1 of IEC 61189-2-807, prepared by IEC/TC 91 “Electronics assembly technology” was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61189-2-807:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national (dop) 2022-07-08 level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with the (dow) 2024-10-08 document have to be withdrawn

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## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu).

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194-2	-	Printed boards design, manufacture and-assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies		-
ISO 11358-1	-	Plastics - Thermogravimetry (TG) of polymers - Part 1: General principles	ofEN ISO 11358-1	-

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IEC 61189-2-807

Edition 1.0 2021-09

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE

**Test methods for electrical materials, printed boards and other interconnection structures and assemblies –  
Part 2-807: Test methods for materials for interconnection structures –  
Decomposition temperature ( $T_d$ ) using TGA**

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**Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles –  
Partie 2-807: Méthodes d'essai des matériaux pour structures d'interconnexion – Température de décomposition ( $T_d$ ) par analyse thermogravimétrique**

INTERNATIONAL  
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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS  
AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****Part 2-807: Test methods for materials for interconnection structures –  
Decomposition temperature ( $T_d$ ) using TGA**

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IEC 61189-2-807 has been prepared by IEC technical committee 91: Electronics assembly technology. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1697/CDV	91/1738/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are described in greater detail at [www.iec.ch/standardsdev/publications](http://www.iec.ch/standardsdev/publications).

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed boards and other interconnection structures and assemblies*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under [webstore.iec.ch](http://webstore.iec.ch) in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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